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Nota di contenuto	ESD BASICS: From Semiconductor Manufacturing to Product Use -- Contents -- About the Author -- Preface -- Acknowledgments -- 1 Fundamentals of Electrostatics -- 1.1 Introduction -- 1.2 Electrostatics -- 1.2.1 Thales of Miletus and Electrostatic Attraction -- 1.2.2 Electrostatics and the Triboelectric Series -- 1.2.3 Triboelectric Series and Gilbert -- 1.2.4 Triboelectric Series and Gray -- 1.2.5 Triboelectric Series and Dufay -- 1.2.6 Triboelectric Series and Franklin -- 1.2.7 Electrostatics - Symmer and the Human Body Model -- 1.2.8

Electrostatics - Coulomb and Cavendish -- 1.2.9 Electrostatics - Faraday and the Ice Pail Experiment -- 1.2.10 Electrostatics - Faraday and Maxwell -- 1.2.11 Electrostatics - Paschen -- 1.2.12 Electrostatics - Stoney and the "Electron" -- 1.3 Triboelectric Charging - How does it Happen? -- 1.4 Conductors, Semiconductors, and Insulators -- 1.5 Static Dissipative Materials -- 1.6 ESD and Materials -- 1.7 Electrification and Coulomb's Law -- 1.7.1 Electrification by Friction -- 1.7.2 Electrification by Induction -- 1.7.3 Electrification by Conduction -- 1.8 Electromagnetism and Electrodynamics -- 1.9 Electrical Breakdown -- 1.9.1 Electrostatic Discharge and Breakdown -- 1.9.2 Breakdown and Paschen's Law -- 1.9.3 Breakdown and Townsend -- 1.9.4 Breakdown and Toepler's Law -- 1.9.5 Avalanche Breakdown -- 1.10 Electroquasistatics and Magnetoquasistatics -- 1.11 Electrodynamics and Maxwell's Equations -- 1.12 Electrostatic Discharge (ESD) -- 1.13 Electromagnetic Compatibility (EMC) -- 1.14 Electromagnetic Interference (EMI) -- 1.15 Summary and Closing Comments -- References -- 2 Fundamentals of Manufacturing and Electrostatics -- 2.1 Materials, Tooling, Human Factors, and Electrostatic Discharge -- 2.1.1 Materials and Human Induced Electric Fields -- 2.2 Manufacturing Environment and Tooling.

2.3 Manufacturing Equipment and ESD Manufacturing Problems -- 2.4 Manufacturing Materials -- 2.5 Measurement and Test Equipment -- 2.5.1 Manufacturing Testing for Compliance -- 2.6 Grounding and Bonding Systems -- 2.7 Worksurfaces -- 2.8 Wrist Straps -- 2.9 Constant Monitors -- 2.10 Footwear -- 2.11 Floors -- 2.12 Personnel Grounding with Garments -- 2.12.1 Garments -- 2.13 Air Ionization -- 2.14 Seating -- 2.15 Carts -- 2.16 Packaging and Shipping -- 2.16.1 Shipping Tubes -- 2.16.2 Trays -- 2.17 ESD Identification -- 2.18 ESD Program Management - Twelve Steps to Building an ESD Strategy -- 2.19 ESD Program Auditing -- 2.20 ESD On-Chip Protection -- 2.21 Summary and Closing Comments -- References -- 3 ESD, EOS, EMI, EMC and Latchup -- 3.1 ESD, EOS, EMI, EMC and Latchup -- 3.1.1 ESD -- 3.1.2 EOS -- 3.1.3 EMI -- 3.1.4 EMC -- 3.1.5 Latchup -- 3.2 ESD Models -- 3.2.1 Human Body Model (HBM) -- 3.2.2 Machine Model (MM) -- 3.2.3 Cassette Model -- 3.2.4 Charged Device Model (CDM) -- 3.2.5 Transmission Line Pulse (TLP) -- 3.2.6 Very Fast Transmission Line Pulse (VF-TLP) -- 3.3 Electrical Overstress (EOS) -- 3.3.1 EOS Sources - Lightning -- 3.3.2 EOS Sources - Electromagnetic Pulse (EMP) -- 3.3.3 EOS Sources - Machinery -- 3.3.4 EOS Sources - Power Distribution -- 3.3.5 EOS Sources - Switches, Relays and Coils -- 3.3.6 EOS Design Flow and Product Definition -- 3.3.7 EOS Sources - Design Issues -- 3.3.8 EOS Failure Mechanisms -- 3.4 EMI -- 3.5 EMC -- 3.6 Latchup -- 3.7 Summary and Closing Comments -- References -- 4 System Level ESD -- 4.1 System Level Testing -- 4.1.1 System Level Testing Objectives -- 4.1.2 Distinction of System and Component Level Testing Failure Criteria -- 4.2 When Systems and Chips Interact -- 4.3 ESD and System Level Failures -- 4.3.1 ESD Current and System Level Failures -- 4.3.2 ESD Induced E- and H-Fields and System Level Failures.

4.4 Electronic Systems -- 4.4.1 Cards and Boards -- 4.4.2 System Chassis and Shielding -- 4.5 System Level Problems Today -- 4.5.1 Hand Held Systems -- 4.5.2 Cell Phones -- 4.5.3 Servers and Cables -- 4.5.4 Laptops and Cables -- 4.5.5 Disk Drives -- 4.5.6 Digital Cameras -- 4.6 Automobiles, ESD, EOS, and EMI -- 4.6.1 Automobiles and ESD - Ignition Systems -- 4.6.2 Automobiles and EMI - Electronic Pedal Assemblies -- 4.6.3 Automobiles and Gas Tank Fires -- 4.6.4 Hybrids and Electric Cars -- 4.6.5 Automobiles in the Future -- 4.7 Aerospace Applications -- 4.7.1 Airplanes, Partial Discharge, and Lightning --

4.7.2 Satellites, Spacecraft Charging, and Single Event Upset (SEU) -- 4.7.3 Space Landing Missions -- 4.8 ESD and System Level Test Models -- 4.9 IEC 61000-4-2 -- 4.10 Human Metal Model (HMM) -- 4.11 Charged Board Model (CBM) -- 4.12 Cable Discharge Event (CDE) -- 4.12.1 Cable Discharge Event (CDE) and Scaling -- 4.12.2 Cable Discharge Event (CDE) - Cable Measurement Equipment -- 4.12.3 Cable Configuration - Test Configuration -- 4.12.4 Cable Configuration - Floating Cable -- 4.12.5 Cable Configuration - Held Cable -- 4.12.6 Cable Discharge Event (CDE) - Peak Current vs. Charged Voltage -- 4.12.7 Cable Discharge Event (CDE) - Plateau Current vs Charged Voltage -- 4.13 Summary and Closing Comments -- References -- 5 Component Level Issues - Problems and Solutions -- 5.1 ESD Chip Protection - The Problem and the Cure -- 5.2 ESD Chip Level Design Solutions - Basics of Design Synthesis -- 5.2.1 ESD Circuits -- 5.2.2 ESD Signal Pin Protection Networks -- 5.2.3 ESD Power Clamp Protection Networks -- 5.2.4 ESD Power Domain-to-Domain Circuitry -- 5.2.5 ESD Internal Signal Line Domain-to-Domain Protection Circuitry -- 5.3 ESD Chip Floor Planning - Basics of Design Layout and Synthesis -- 5.3.1 Placement of ESD Signal Pin HBM Circuitry.

5.3.2 Placement of ESD Signal Pin CDM Circuitry -- 5.3.3 Placement of ESD Power Clamp Circuitry -- 5.3.4 Placement of ESD VSS-to-VSS Circuitry -- 5.4 ESD Analog Circuit Design -- 5.4.1 Symmetry and Common Centroid Design for ESD Analog Circuits -- 5.4.2 Analog Signal Pin to Power Rail ESD Network -- 5.4.3 Common Centroid Analog Signal Pin to Power Rail ESD Network -- 5.4.4 Co-synthesis of Common Centroid Analog Circuit and ESD Networks -- 5.4.5 Signal Pin-to-Signal Pin Differential Pair ESD Network -- 5.4.6 Common Centroid Signal Pin Differential Pair ESD Protection -- 5.5 ESD Radio Frequency (RF) Design -- 5.5.1 ESD Radio Frequency (RF) Design Practices -- 5.5.2 ESD RF Circuits - Signal Pin ESD Networks -- 5.5.3 ESD RF Circuits - ESD Power Clamps -- 5.5.4 ESD RF Circuits - ESD RF VSS-to-VSS Networks -- 5.6 Summary and Closing Comments -- References -- 6 ESD in Systems - Problems and Solutions -- 6.1 ESD System Solutions from Largest to Smallest -- 6.2 Aerospace Solutions -- 6.3 Oil Tanker Solutions -- 6.4 Automobile Solutions -- 6.5 Computers - Servers -- 6.5.1 Servers - Touch Pads and Handling Procedures -- 6.6 Mother Boards and Cards -- 6.6.1 System Card Insertion Contacts -- 6.6.2 System Level Board Design - Ground Design -- 6.7 System Level "On Board" ESD Protection -- 6.7.1 Spark Gaps -- 6.7.2 Field Emission Devices (FED) -- 6.8 System Level Transient Solutions -- 6.8.1 Transient Voltage Suppression (TVS) Devices -- 6.8.2 Polymer Voltage Suppression (PVS) Devices -- 6.9 Package-Level Mechanical ESD Solutions - Mechanical "Crowbars" -- 6.10 Disk Drive ESD Solutions -- 6.10.1 In Line "ESD Shunt" -- 6.10.2 Armature - Mechanical "Shunt" - A Built-In Electrical "Crowbar" -- 6.11 Semiconductor Chip Level Solutions - Floor Planning, Layout, and Architecture -- 6.11.1 Mixed Signal Analog and Digital Floor Planning.

6.11.2 Bipolar-CMOS-DMOS (BCD) Floor Planning -- 6.11.3 System-on Chip Design Floor Planning -- 6.12 Semiconductor Chip Solutions - Electrical Power Grid Design -- 6.12.1 HMM and IEC Specification Power Grid and Interconnect Design Considerations -- 6.12.2 ESD Power Clamp Design Synthesis - IEC 61000-4-2 Responsive ESD Power Clamps -- 6.13 ESD and EMC - When Chips Bring Down Systems -- 6.14 System Level and Component Level ESD Testing and System Level Response -- 6.14.1 Time Domain Reflection (TDR) and Impedance Methodology for ESD Testing -- 6.14.2 Time Domain Reflectometry (TDR) ESD Test System Evaluation -- 6.14.3 ESD Degradation System

	Level Method - Eye Tests -- 6.15 EMC and ESD Scanning -- 6.16 Summary and Closing Comments -- References -- 7 Electrostatic Discharge (ESD) in the Future -- 7.1 What is in the Future for ESD? -- 7.2 Factories and Manufacturing -- 7.3 Photo-Masks and Reticles -- 7.3.1 ESD Concerns in Photo-Masks -- 7.3.2 Avalanche Breakdown in Photo-Masks -- 7.3.3 Electrical Model in Photo-Masks -- 7.3.4 Failure Defects in Photo-Masks -- 7.4 Magnetic Recording Technology -- 7.5 Micro-Electromechanical (MEM) Devices -- 7.5.1 ESD Concerns in Micro-Electromechanical (MEM) Devices -- 7.6 Micro-Motors -- 7.6.1 ESD Concerns in Micro-Motors -- 7.7 Micro-Electromechanical (MEM) RF Switches -- 7.7.1 ESD Concerns in Micro-Electromechanical (MEM) RF Switches -- 7.8 Micro-Electromechanical (MEM) Mirrors -- 7.8.1 ESD Concerns in Micro-Electromechanical (MEM) Mirrors -- 7.9 Transistors -- 7.9.1 Transistors - Bulk vs. SOI Technology -- 7.9.2 Transistors and FinFETs -- 7.9.3 ESD in FinFETs -- 7.10 Silicon Nanowires -- 7.11 Carbon Nanotubes -- 7.12 Future Systems and System Designs -- 7.13 Summary and Closing Comments -- References -- Glossary -- ESD Standards -- Index.
Sommario/riassunto	This title introduces the fundamentals of ESD, electrical overstress (EOS), electromagnetic interference (EMI), electromagnetic compatibility (EMC), and latchup, as well as provides a coherent overview of the semiconductor manufacturing environment and the final system assembly.